



Click [here](#) for the 3D model.

Dimensions	
Chip Size	0402
L	1mm +/-0.05mm
W	0.5mm +/-0.05mm
T	0.5mm +/-0.05mm
S	0.3mm MIN
B	0.3mm +/-0.1mm

Packaging Specifications	
Packaging	T&R, 180mm, Paper Tape
Packaging Quantity	10000

General Information	
Series	SMD Comm X8R HT150C
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Component Weight	1.21 mg
Shelf Life	78 Weeks
MSL	1

Specifications	
Capacitance	300 pF
Measurement Condition	1 MHz 1.0Vrms
Capacitance Tolerance	1%
Voltage DC	10 VDC
Dielectric Withstanding Voltage	25 VDC
Temperature Range	-55/+150°C
Temperature Coefficient	X8R
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	15%, 1MHz 1.0Vrms
Dissipation Factor	2.5% 1MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	100 GOhms